

40× CD-ROM Decoder with SCSI Interface

Functions

- CD-ROM ECC function
- SCSI I/F function
- Subcode I/F function
- · CAV audio function

Features

- SCSI interface (includes on-chip SCAM selection register)
- Supports 20× speed and a 10 MBytes/s transfer rate when using 16-bit 70-ns EDO DRAM
- Supports 40× speed and a 10 MB/s transfer rate when using 16-bit 50-ns EDO DRAM
- Up to 4 M bits of buffer RAM can be used.
- The user can freely set up the CD main channel and the C2 flag areas in buffer RAM.
- Batch transfer function (Allows the CD main channel, the C2 flags, and other data to be sent in a single operation.)
- Multi-block transfer function (Allows multiple blocks to be sent automatically in a single operation.)
- · Subcode buffering and CD-TEXT support

Specifications

Absolute Maximum Ratings at $V_{SS} = 0 \text{ V}$

•	CA	V	audio)]	tunc	tion
---	----	---	-------	-----	------	------

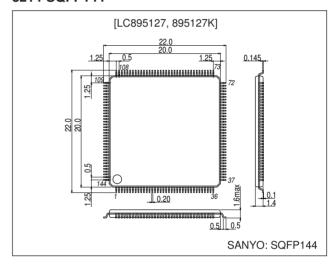
• Supports 20 MBytes/s transfers

• Package: SQFP-144

Package Dimensions

unit: mm

3214-SQFP144



Parameter	Symbol	Conditions	Ratings	Unit
Maximum supply voltage	V _{DD} max	Ta = 25°C	-0.3 to +7.0	V
Input/output voltage	V _I , V _O	Ta = 25°C	-0.3 to $V_{DD} + 0.3$	V
Allowable power dissipation	Pd max	Ta ≤ 70°C	550	mW
Operating temperature	Topr		-30 to +70	°C
Storage temperature	Tstg		-55 to +125	°C
Soldering temperature (pin part only)		10 s	260	°C

Allowable Operating Ranges at Ta = -30° C to $+70^{\circ}$ C, $V_{SS} = 0$ V

Parameter	Symbol	Conditions	Ratings			Unit
Faidiletei	Symbol	Conditions	min	typ	max	
Supply voltage	V_{DD}		4.5	5.0	5.5	V
Input voltage range	V_{IN}		0		V_{DD}	V

- Any and all SANYO products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your SANYO representative nearest you before using any SANYO products described or contained herein in such applications.
- SANYO assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all SANYO products described or contained herein.

DC Characteristics at Ta = -30 to +70°C, V_{SS} = 0 V, V_{DD} = 4.5 to 5.5 V

Parameter	Cumbal	Conditions	Applicable pine		Ratings			
Parameter	Symbol	Conditions	Applicable pins	min	typ	max	Unit	
Input high-level voltage	V _{IH1}	TTL levels	(1)	2.2			V	
Input low-level voltage	V _{IL1}	TTL levels	(1)			0.8	V	
Input high-level voltage	V _{IH2}	TTL levels	(9)	2.2	_	_	V	
Input low-level voltage	V _{IL2}	with pull-up resistor	(9)	_	_	0.8	V	
Input high-level voltage	V _{IH3}	TTL levels	(2)	2.2	_	_	V	
Input low-level voltage	V _{IL3}	Schmitt	(2)	_	1	0.8	V	
Input high-level voltage	V _{IH4}	CMOS levels	(3)	0.8 V _{DD}	_	_	V	
Input low-level voltage	V _{IL4}	Schmitt	(3)	_	_	0.2 V _{DD}	V	
Input high-level voltage	V _{IH5}		(4), (8), (10)	2.0		_	V	
Input low-level voltage	V _{IL5}		(4), (6), (10)			0.8	V	
Input high-level voltage	V _{IH2}	TTL levels	(11)	2.2		_	V	
Input low-level voltage	V _{IL2}	with pull-up resistor	(11)	_	_	0.8	V	
Output high-level voltage	V _{OH1}	I _{OH1} = -12 mA	(6)	V _{DD} – 2.1	_	_	V	
Output low-level voltage	V _{OL1}	I _{OL1} = 12 mA	(0)	_	_	0.4	V	
Output high-level voltage	V _{OH2}	$I_{OH2} = -8 \text{ mA}$	(7)	2.4			V	
Output low-level voltage	V _{OL2}	I _{OL2} = 8 mA	(1)			0.4	V	
Output high-level voltage	V _{OH2}	I _{OH2} = -2 mA	(9), (5), (11)	2.4			V	
Output low-level voltage	V _{OL2}	I _{OL2} = 2 mA	(9), (3), (11)			0.4	V	
Output low-level voltage	V _{OL4}	I _{OL4} = 48 mA	(10)			0.4	V	
Input leakage current	I _{IL}	$V_{I} = V_{SS}, V_{DD}$	All input pins	-25		+25	μΑ	
Pull-up resistance	R _{UP}		(5), (9), (11)	60	120	240	kΩ	

Applicable pin sets are as follows.

INPUT

- (1) TEST0 to TEST4, CSCTRL, SUA0 to SUA6, C2P0, SDATA, BCK, LRCK, SCOR, WFCK, SBS0, MCK2SEL
- (2) RESET
- (3) \overline{CS} , \overline{RD} , \overline{WR}
- (4) SCSISEL, XTALSEL

OUTPUT

- (5) $\overline{INT0}$, $\overline{INT1}$, \overline{SWAIT}
- (6) MCK
- (7) EXCK, DSDATA, DLRCK, DBCK, \overline{RASO} , \overline{CASO} , \overline{CASO} , \overline{OE} , \overline{UWE} , \overline{LWE} , RA0 to RA8

INOUT

- (8) \overline{ACK} , \overline{ATN}
- (9) D0 to D7, IO0 to IO15, IOP0 to IOP7
- (10) $\overline{DB0}$ to $\overline{DB7}$, \overline{DBP} , \overline{BSY} , I/O, \overline{MSG} , \overline{SEL} , \overline{RST} , \overline{REQ} , C/D
- (11) IOP0 to IOP7

Note: Pins XTAL0, XTALCK0, XTAL1, XTALCK1, and X1EN are not included in DC characteristics.

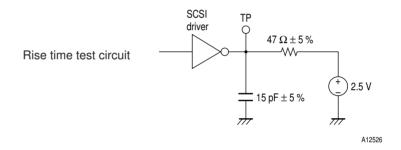
SCSI Pin Input Characteristics

Parameter	Symbol	Conditions		Unit		
Farameter	Syllibol	Conditions	min	typ	max	
Input threshold voltage	V _{t+t1}	V _{DD} = 4.50 to 5.50 V		1.60	2.00	V
input tireshold voltage	V _{t-t1}	V _{DD} = 4.30 to 3.30 V	0.80	1.10		V
Hysteresis width	ΔV_{tt1}	V _{DD} = 5.0 V	0.41	0.5		٧

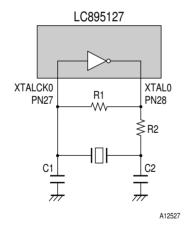
Active-Low Output Characteristics

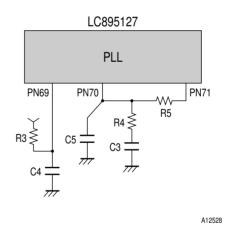
Parameter	Symbol	Conditions	Ratings			
Falametei	Syllibol	Conditions	min	typ	max	Unit
Output high-level voltage	V _{OH}		2.5			V
Output low-level voltage	V _{OL}				0.4	V

Note: Only applies to the active-low output pins $\overline{\mathsf{DB0}}$ to $\overline{\mathsf{DB7}}$, $\overline{\mathsf{REQ}}$, $\overline{\mathsf{DBPB}}$



Recommended Oscillator and PLL Circuits





 $R1 = 120 \text{ k}\Omega$, $R2 = 47 \Omega$, C1 = 30 pF

Crystal oscillator frequency XTALCK0 = 16.9344 MHz

$$R3 = 7.5 \text{ k}\Omega, \, R4 = 200 \, \Omega, \, R5 = 10 \text{ k}\Omega, \, C3 = 0.1 \, \mu\text{F}$$

 $C4 = 0.1 \mu F$, $C5 = 0.002 \mu F$ to $0.01 \mu F$

Note: The values listed above for R3, R4, R5, and C3 also apply when the XTALKC0 frequency is 33.8688 MHz.

Applications must be designed so that the analog V_{DD} and V_{SS} power supply system is completely independent of the logic system power supply and is not affected by the logic system power supply fluctuation in any way.

Note: Since the exact values of these components will vary depending on the characteristics of the printed circuit board used and other factors, consult the manufacturer of the crystal element when designing the oscillator circuit.

Pin Functions

Туре						
	I	INPUT	В	BIDIRECTION	NC	NOT CONNECT
	0	OUTPUT	Р	POWER		

Pin No.	Pin name	Туре	Pin functions
1	V _{SS0}	P	
2	IO2	В	
3	IO1	В	Buffer RAM data I/O
4	100	В	These pins have built-in pull-up resistors.
5	MCK2SEL	ı	PLL frequency selection. Currently, this pin must be connected to V _{DD} .
6	C2PO	i	- 12 moquandy conscions can analy, and part made as commoded to Topic
7	SDATA	i	
8	BCK	i	CD DSP interface
9	LRCK	i	
10	EXCK	0	Subcode I/O
11	WFCK	i	
12	SBSO		
13	SCOR	ı	Subcode I/O
14	DSDATA	0	
15	DLRCK	0	D/A converter outputs
16	DBCK	0	
17	MCK	0	XTALCLK0 1/1, 1/2, and stop output
18	V _{DD}	Р	
19	V _{SS0}	Р	
20	RESET	ı	IC reset. The IC is reset on a low-level input
21	CSCTRL	ı	MC (Microcontroller) CSL ₀ , Hi
22	TEST3	ı	
23	TEST0	ı	
24	TEST1	ı	Test pins. These pins must be connected to V _{SS0} in normal operation.
25	TEST2	ı	
26	V _{SS0}	Р	
27	XTALCK0	1	Crystal oscillator circuit input
28	XTAL0	0	Crystal oscillator circuit output
29	TEST4	ı	Test pin. This pin must be connected to V _{SS0} in normal operation.
30	V _{SS0}	Р	
31	V _{SS0}	Р	
32	V _{SS0}	Р	
33	V _{SS0}	Р	
34	IOP7	I	0 10 17 10 17 17 17 17 17 17 17 17 17 17 17 17 17
35	IOP6	ı	General-purpose I/O ports. These pins include built-in pull-up resistors.
36	V _{SS0}	Р	
37	V_{DD}	Р	
38	IOP5	I	
39	IOP4	ı	
40	IOP3	ı	Canaval numana I/O narta. These pine include built in million markets
41	IOP2	1	General-purpose I/O ports. These pins include built-in pull-up resistors.
42	IOP1	1	
43	IOP0	1	
44	V _{SS0}	Р	
45	RD	I	Microcontroller data read signal input
46	WR	I	Microcontroller data write signal input
47	CS	I	Register chip select input from the microcontroller
48	SUA0	I	
49	SUA1	I	
50	SUA2	I	Microcontroller register selection signals
51	SUA3	I	
52	SUA4	ı	
53	SUA5	I	Continued on next page

Continued on next page.

Continued from preceding page.

Pin No.	Pin	I/O	Function
54	V _{DD}	Р	
55	V _{SS0}	Р	
56	SUA6	I	Microcontroller register selection signals
57	D0	В	
58	D1	В	
59	D2	В	Missasantvallay data signala
60	D3	В	Microcontroller data signals
61	D4	В	
62	D5	В	
63	V_{SS0}	Р	
64	D6	В	Microcontroller data signals
65	D7	В	Wild Occurroller data signals
66	ĪNT0	0	Interrupt request signal output to the microcontroller (ECC side. Set by setting a register value.)
67	ĪNT1	0	Interrupt request signal output to the microcontroller (SCSI side. Set by setting a register value.)
68	SWAIT	0	Wait signal output to the microcontroller
69	X1EN	I	Used by the PLL. This pin must be connected to V _{DD} through a resistor.
70	XTALCK1	I	Used by the PLL.
71	XTAL1	0	Used by the PLL.
72	V _{SS0}	Р	Analog V _{SS}
73	V_{DD}	Р	Analog V _{DD}
74		NC	
75	I/O	В	SCSI interface
76	REQ	В	
77	V _{SS1}	Р	
78	C/D	В	SCSI interface
79	SEL	В	
80		NC -	
81	V _{DD}	P	
82	V _{SS1}	P	
83	MSG	В	SCSI interface
84	RST	B P	
85 86	V _{SS1} ACK	В	
87	BSY	В	SCSI interface
88		В	
89	V _{SS1} ATN	В	SCSI interface
90	V _{DD}	P	3001 Interlace
91	V _{SS1}	P	
92	*351	NC	
93	DBP	В	SCSI interface
94	V _{DD}	P	***
95	DB7	В	
96	DB6	В	SCSI interface
97	V _{SS1}	P	
98	DB5	В	
99	DB4	В	SCSI interface
100	V _{DD}	Р	
101	DB3	В	00011111
102	DB2	В	SCSI interface
103	V _{SS1}	Р	
104	DB1	В	CCCI interface
105	DB0	В	SCSI interface
106	SCSISEL	I	SCSI pin layout selection. (This pin must be connected to V _{SS0} .)
107	XTALSEL	I	PLL XTAL oscillator selection

Continued on next page.

Continued from preceding page.

Pin No.	Pin	I/O	Function
108	V _{SS1}	Р	
109	V_{DD}	Р	
110	V _{SS0}	Р	
111	RAS0	0	Buffer RAM RAS signal output 0
112	V_{DD}	Р	
113	CAS0	0	Buffer RAM CAS signal output 0 (Normally held fixed at 0 (low).)
114	CAS1	0	Buffer RAM RAS signal output 1
115	ŌĒ	0	Buffer RAM output enable
116	UWE (RA9)	0	Buffer RAM upper write enable (RA9 when 8M or more DRAM is used.)
117	LWE	0	Buffer RAM lower write enable
118	V _{SS0}	Р	
119	RA0	0	
120	RA1	0	
121	RA2	0	
122	RA3	0	Buffer RAM address signal outputs
123	RA4	0	
124	RA5	0	
125	RA6	0	
126	V_{DD}	Р	
127	V _{SS0}	Р	
128	RA7	0	Duffey DAM address signal outputs
129	RA8	0	Buffer RAM address signal outputs
130	IO15	В	
131	IO14	В	
132	IO13	В	
133	IO12	В	Buffer RAM data I/O
134	IO11	В	These pins have built-in pull-up resistors.
135	IO10	В	
136	IO9	В	
137	IO8	В	
138	V _{SS0}	Р	
139	107	В	
140	IO6	В	Puffer PAM data I/O
141	IO5	В	Buffer RAM data I/O
142	IO4	В	These pins have built-in pull-up resistors.
143	IO3	В	
144	V_{DD}	Р	

Unused ("NC") pins must be left open.

Pins whose name is under a bar operate with inverted (negative) logic.

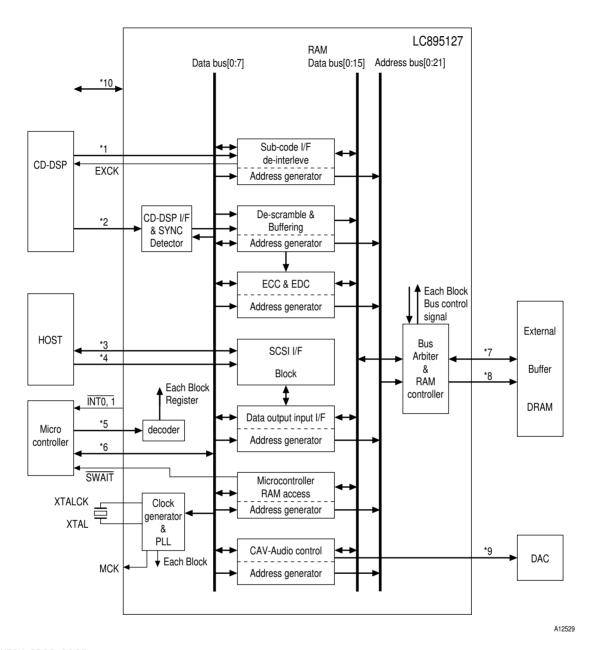
V_{SS0} is the logic system ground and V_{SS1} is the SCSI interface driver ground.

If DRAM is used, applications must adopt measures to prevent undershoot and other DRAM problems. Such measures include inserting resistors in the RAS

and CAS lines and inserting capacitors between V_{SS} pins.

See the article on Designing with the Latest Microcontrollers and Memory in special issue number 25 of Transistor Technology for details on these measures. Since this device includes buffers that sink a current of 48 mA, applications must take adequate noise prevention measures.

Block Diagram



- *1 WFCK, SBSO, SCOR
- *2 BCK, SDATA, LRCK, C2PO
- *3 $\overline{DB0}$ to $\overline{DB7}$, \overline{DBP} , \overline{BSY} , \overline{MSG} , \overline{SEL} , \overline{RST} , \overline{REQ} , I/O, C/D
- *4 ACK, ATN
- *5 \overline{RD} , \overline{WR} , SUA0 to SUA6, ZCS, CSCTRL
- *6 D0 to D7
- *7 IO0 to IO15
- *8 RA0 to RA10, $\overline{RAS1}$, $\overline{CAS0}$, $\overline{CAS1}$, \overline{OE} , \overline{UWE} , \overline{LWE}
- *9 DBCK, DLRCK, DSDATA
- *10 IOP7 to IOP0

- Specifications of any and all SANYO products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- SANYO Electric Co., Ltd. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.
- In the event that any or all SANYO products (including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of SANYO Electric Co., Ltd.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the SANYO product that you intend to use.
- Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production. SANYO believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.

This catalog provides information as of December, 1999. Specifications and information herein are subject to change without notice.